

## Features

- Schottky barrier diodes
- Low forward voltage drop
- High Junction Temperature
- Moisture sensitivity: level 1, per J-STD-020
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Add suffix "E" for Halogen Free
- Halogen-free according to IEC 61249-2-21 definition
- AEC-Q101 qualified



DO-214AA (SMB)

## Typical Applications

For use in low voltage, high frequency inverters, free wheeling, and polarity protection application

<b>Maximum Ratings</b> (TA = 25 °C unless otherwise noted)			
Parameter	Symbol	SK3C0B SK3C0BE	Unit
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	200	V
Maximum RMS voltage	V <sub>RMS</sub>	140	V
Maximum DC blocking voltage	V <sub>DC</sub>	200	V
Maximum average forward rectified current	I <sub>F(AV)</sub>	3.0	A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	100	A
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>STG</sub>	- 55 to + 150	°C

<b>Electrical Characteristics</b> (TA = 25 °C unless otherwise noted)				
Parameter	Test Conditions	Symbol	SK3C0B SK3C0BE	Unit
Maximum instantaneous forward voltage	I <sub>F</sub> =3A, T <sub>A</sub> =25°C	V <sub>F</sub>	0.85	V
Maximum DC reverse current at rated DC blocking voltage	T <sub>A</sub> =25°C	I <sub>R</sub>	30	µA
	T <sub>A</sub> =125°C		1000	
Typical junction capacitance	4.0 V, 1 MHz	C <sub>J</sub>	80	pF

<b>Thermal Characteristics</b>			
Parameter	Symbol	SK3C0B SK3C0BE	Unit
Typical thermal resistance <sup>(1)</sup>	R <sub>θJA</sub>	70	°C/W
	R <sub>θJC</sub>	28	
	R <sub>θJL</sub>	15	

Note1: Thermal resistance from junction to lead, mounted on PCB with 8.0×8.0mm copper pads

## Ratings and Characteristics Curves

(TA = 25°C unless otherwise noted)

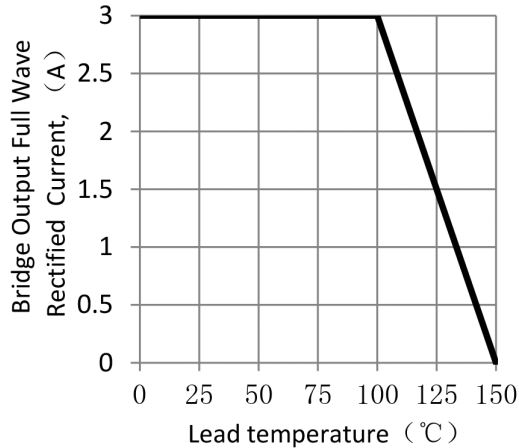


Figure 1. Forward Current Derating Curve

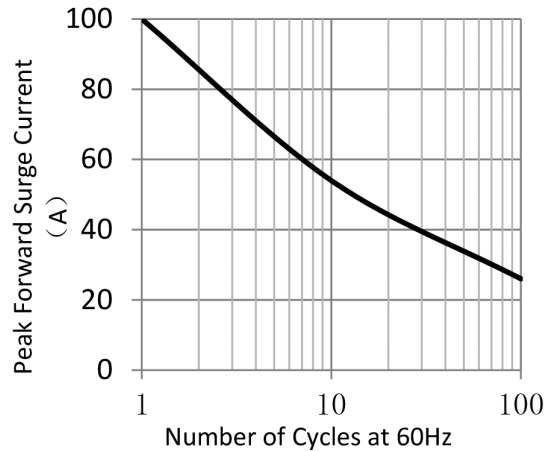


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

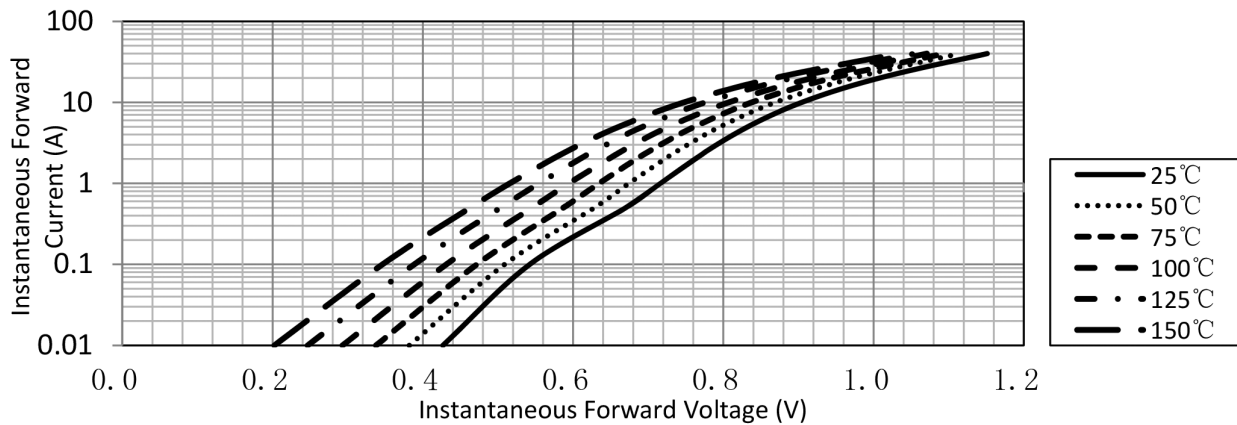


Figure 3. Typical Instantaneous Forward Characteristics

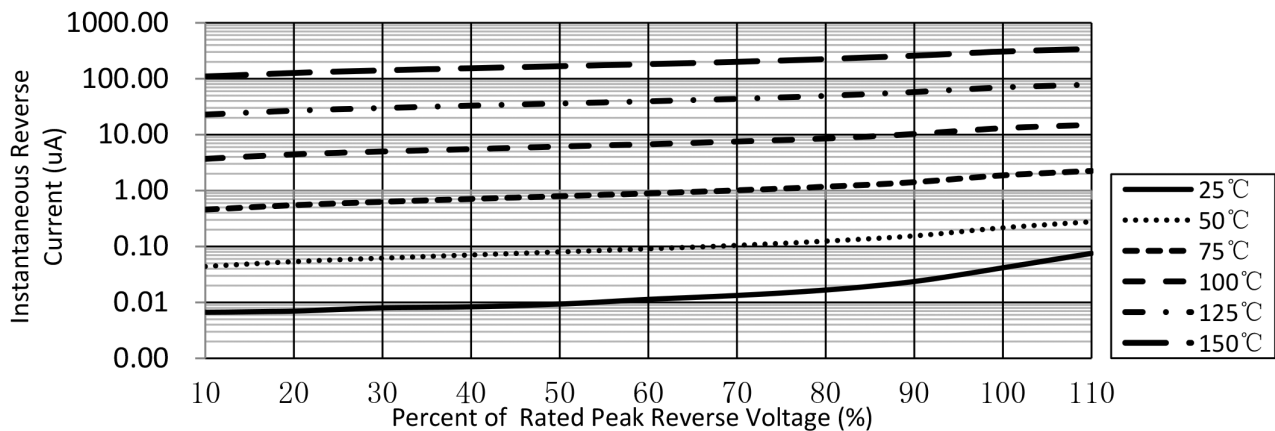
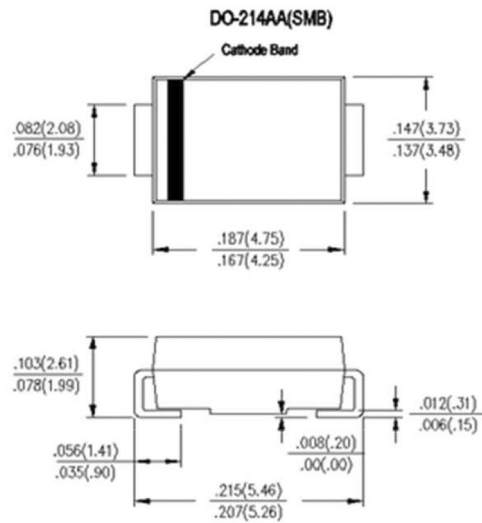


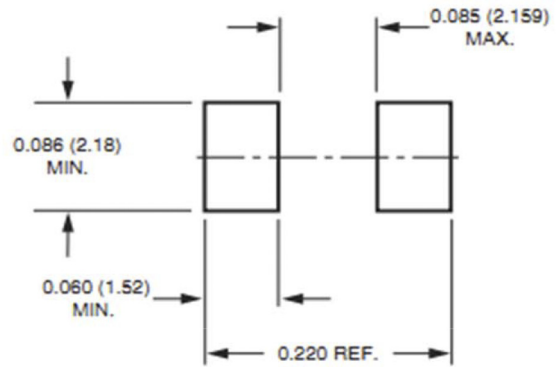
Figure 4. Typical Reverse Characteristics

## Package Outline Dimensions

in inches (millimeters)



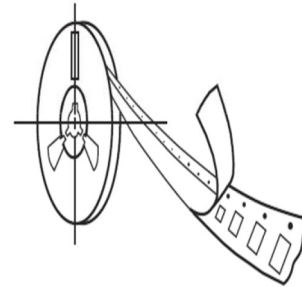
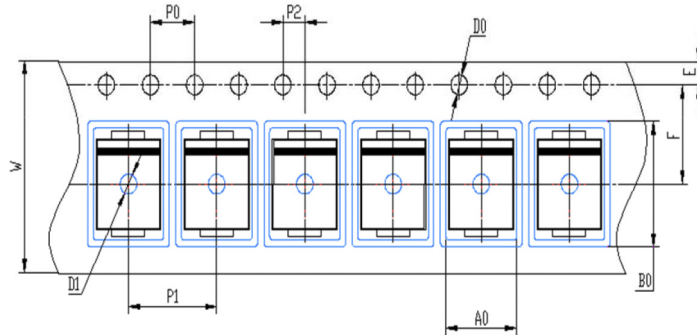
## Mounting Pad Layout



## Packing Information

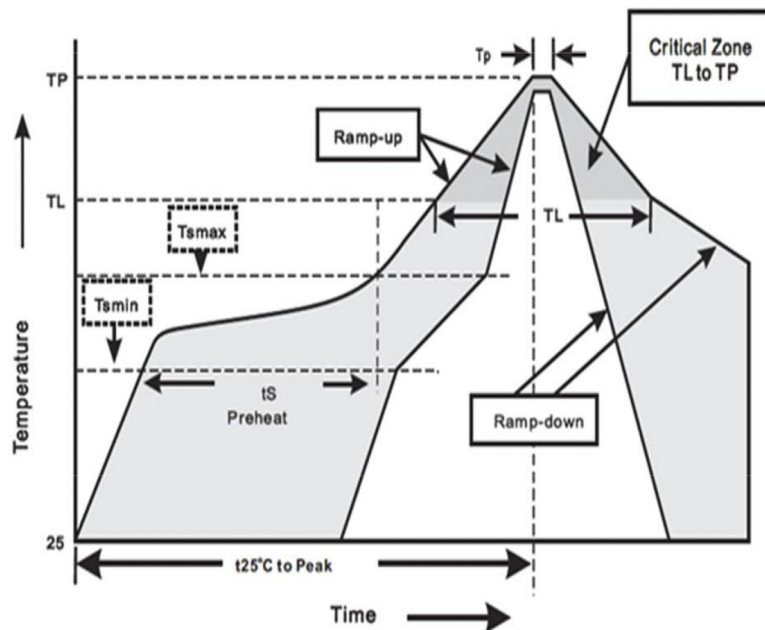
3000 pcs/Reel, 18 Reels/Box; 12mm Tape, 13" Reel

## Tape & Reel Specification



Symbol	SMB (mm)
W	12 ± 0.2
E	1.75 ± 0.1
F	5.5 ± 0.05
D0	1.5 ± 0.1
D1	1.50 +0.1/-0
P0	4.0 ± 0.1
P1	8.0 ± 0.1
P2	2.0 ± 0.05
A0	3.95 ± 0.1
B0	5.74 ± 0.1

## Soldering Parameters



Reflow Soldering		Sn-Pb Eutectic Assembly	Pb-Free assembly
Pre Heat	- Temperature Min ( $T_s(min)$ )	100°C	150°C
	- Temperature Max ( $T_s(max)$ )	150°C	200°C
	- Time (min to max) (ts)	60 – 120 secs	60 – 180 secs
Average ramp up rate (Liquidus) Temp ( $T_L$ ) to peak		3°C/second max	3°C/second max
TS(max) to $T_L$ - Ramp-up Rate		3°C/second max	3°C/second max
Reflow	- Temperature ( $T_L$ ) (Liquidus)	183°C	217°C
	- Time (min to max) (ts)	60 – 150 seconds	60 – 150 seconds
Peak Temperature ( $T_P$ )		240+0/-5 °C	240+0/-5°C
Time within 5°C of actual peak Temperature ( $t_p$ )		10 – 30 seconds	20 – 40 seconds
Ramp-down Rate		6°C/second max	6°C/second max
Time 25°C to peak Temperature ( $T_P$ )		6 minutes Max.	8 minutes Max.
Do not exceed		260°C	260°C

Wave Soldering	
Peak Temperature :	260+0/-5°C
Dipping Time :	10 seconds
Soldering :	1 time